

- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

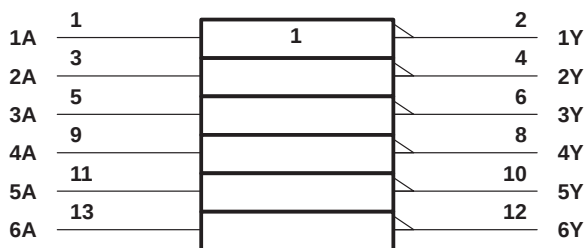
These devices contain six independent inverters. They perform the Boolean function $Y = \bar{A}$.

The SN54F04 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74F04 is characterized for operation from 0°C to 70°C .

FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic symbol†



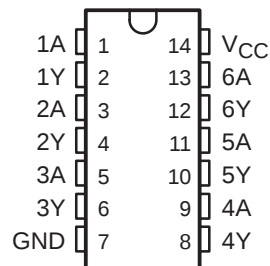
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each inverter (positive logic)

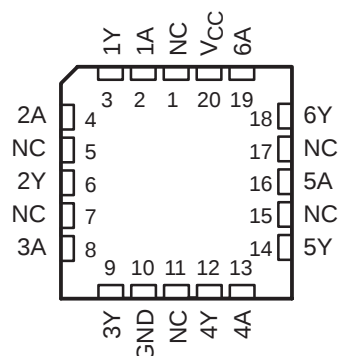


Pin numbers shown are for the D, J, and N packages.

SN54F04 ... J PACKAGE
SN74F04 ... D OR N PACKAGE
(TOP VIEW)



SN54F04 ... FK PACKAGE
(TOP VIEW)



NC – No internal connection

SN54F04, SN74F04

HEX INVERTERS

SDFS037A – MARCH 1987 – REVISED OCTOBER 1993

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–1.2 V to 7 V
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the high state	–0.5 V to V_{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range: SN54F04	–55°C to 125°C
SN74F04	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		SN54F04			SN74F04			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			–18			–18	mA
I_{OH}	High-level output current			–1			–1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54F04			SN74F04			UNIT
			MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V_{IK}	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			–1.2			–1.2	V
V_{OH}	$V_{CC} = 4.5$ V,	$I_{OH} = -1$ mA	2.5	3.4		2.5	3.4		V
	$V_{CC} = 4.75$ V,	$I_{OH} = -1$ mA				2.7			
V_{OL}	$V_{CC} = 4.5$ V,	$I_{OL} = 20$ mA		0.3	0.5		0.3	0.5	V
I_I	$V_{CC} = 5.5$ V,	$V_I = 7$ V			0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V			20			20	μA
I_{IL}	$V_{CC} = 5.5$ V,	$V_I = 0.5$ V			–0.6			–0.6	mA
$I_{OS}^{\S}$	$V_{CC} = 5.5$ V,	$V_O = 0$	–60		–150	–60		–150	mA
I_{CCH}	$V_{CC} = 5.5$ V,	$V_I = 0$		2.8	4.2		2.8	4.2	mA
I_{CCL}	$V_{CC} = 5.5$ V,	$V_I = 4.5$ V		10.2	15.3		10.2	15.3	mA

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

^{\S} Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.



switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, C _L = 50 pF, R _L = 500 Ω, T _A = 25°C			V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX†				UNIT
			‘F04			SN54F04		SN74F04		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	1.6	3.3	5	1.2	7	1.6	6	ns
t _{PHL}			1	2.8	4.3	1	6.5	1	5.3	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9759301Q2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
5962-9759301QCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
5962-9759301QDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/33002B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/33002BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/33002BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN54F04J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN74F04D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74F04DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74F04N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74F04N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74F04NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54F04FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54F04J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54F04W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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